



## Features 特性

- High Enthalpy 高焓值
- Good Mechanical Strength 机械强度高
- Excellent Processing Performance 加工性能好
- Excellent Reliability 高可靠性

## Applications 产品应用

- Action Camera 运动相机
- Smart Watch / Phone 智能手表/手机
- Virtual Reality 虚拟现实设备
- Unmanned Aerial Vehicle 无人机

**Thermal TSP0060-37** 是一种既可以导热又可以储热的有机硅体系垫片产品，材料可以根据终端产品的使用场景进行不同形状的定制加工，在紧凑型智能终端产品上有很好的应用前景。

**Thermal TSP0060-37** is a kind of silicone-based gap pad material with both thermal conductive and heat storage functionality. The product can be customized to different dimension based on terminal application scenarios, which has good prospect to be used in compact intelligent terminal applications.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
Color 颜色	Gray 灰色	—	Visual 目视
Thermal Conductivity 导热系数	0.6	W/m·K	ASTM D5470
Enthalpy 焓值	90	J/cm <sup>3</sup>	ASTM D3418
Phase Change Temperature 相变化温度	37	°C	ASTM D3418
Density 密度	1.6	g/cm <sup>3</sup>	ASTM D792
Hardness 硬度 (Shore A)	70	—	ASTM D2240
Temperature Range 耐温范围	-40 - 100	°C	—
RoHS Compliance 合规性	YES	—	—
Shelf Life 保存期	12	month	25±5°C, 50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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